



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLF4949EJ	Issued	03. May 2021
MA#	MA001001408		
Package	PG-DSO-8-52	Weight*	83.61 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.577	0.69	0.69	6902	6902
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8704	
	non noble metal	copper	7440-50-8	29.548	35.34	36.26	353406	362654
wire	non noble metal	copper	7440-50-8	0.086	0.10	0.10	1029	1029
encapsulation	organic material	carbon black	1333-86-4	0.102	0.12		1218	
	plastics	epoxy resin	-	4.686	5.60		56042	
	inorganic material	silicondioxide	60676-86-0	46.142	55.20	60.92	551891	609151
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8314	8314
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8665	8665
glue	plastics	epoxy resin	-	0.069	0.08		821	
	noble metal	silver	7440-22-4	0.206	0.25	0.33	2464	3285
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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